

Meeting Purpose: The objective for this meeting is for feedback on the detailed design on the thermal components of the enclosure subsystem.

Materials to be Reviewed: *Detailed Design Review Package, Mechanical Engineering Section, Rev. 02*

Meeting Date: 02/12/09

Meeting Location: 09-2061

Meeting Time: 11:30 AM – 11:50 AM

Timeline:

| Meeting Timeline | | |
|------------------|---|----------------------------|
| Start Time | Topic of Review | Required Attendees |
| 11:30 | Specifications Review | Dr. Bailey, Anthony Berwin |
| 11:35 | Enclosure Subsystem Review <ul style="list-style-type: none"> • Part Models • Assembly Models • Part Drawings • List of Materials | Dr. Bailey, Anthony Berwin |
| 11:40 | Thermal Analysis <ul style="list-style-type: none"> • Hand Analysis • Computer Analysis | Dr. Bailey, Anthony Berwin |